Vincotech

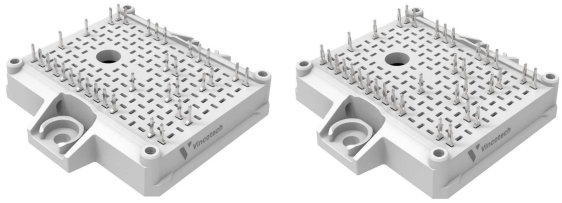
10-E212PMA035SC-L188A48Z
10-EY12PMA035SC-L188A48T
datasheet

flowPIM E2 **1200 V / 35 A**

Features

- Trench IGBT4 technology
- Standard industrial housing
- Optimized $R_{th(j-s)}$ with Phase Change Material
- Built-in NTC

flow E2 12 mm housing



Solder pin Press-fit pin

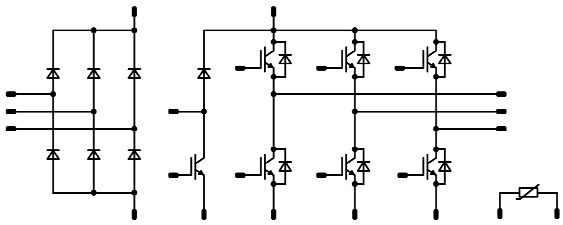
Target applications

- Industrial Drives

Types

- 10-E212PMA035SC-L188A48Z
- 10-EY12PMA035SC-L188A48T

Schematic



Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C		35	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	105	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	116	W
Gate-emitter voltage	V_{GES}		±20	V
Short circuit ratings	t_{SC}	T_j ≤ 150 °C V_{GE} = 15 V V_{CC} = 800 V	10	µs
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ T_s = 80 °C	43	A
Repetitive peak forward current	I_{FRM}		70	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	80	W
Maximum junction temperature	T_{jmax}		175	°C
Brake Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C		35	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	105	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	116	W
Gate-emitter voltage	V_{GES}		±20	V
Short circuit ratings	t_{SC}	$T_j \leq$ 150 °C V_{GE} = 15 V V_{CC} = 800 V	10	µs
Maximum junction temperature	T_{jmax}		175	°C
Brake Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F		10	A
Repetitive peak forward current	I_{FRM}		20	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	50	W
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Diode				
Peak repetitive reverse voltage	V_{RRM}		1600	V
Continuous (direct) forward current	I_F		45	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave T_j = 150 °C, t_p = 10 ms	350	A
Surge current capability	I^2t		610	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	60	W
Maximum junction temperature	T_{jmax}		150	°C
Module Properties				
General Properties				
Stray inductance	L_P		30	nH
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	6000	V
		AC Voltage t_p = 1 min	2500	V
Creepage distance			min. 12,7	mm
Clearance		Solder pin / Press-fit pin	8,85 / 8,83	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,0012	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		35	25 150	1,58	1,87 2,30	2,07	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			5	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}	f= 1 Mhz	0	25		25		2000		pF
Reverse transfer capacitance	C_{res}							70		
Gate charge	Q_g		-15/15			25		270		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,82		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 16 Ω R_{goff} = 16 Ω	±15	600	35	25 150		85 89		ns
Rise time	t_r					25 150		22 26		
Turn-off delay time	$t_{d(off)}$					25 150		199 259		
Fall time	t_f					25 150		73 115		
Turn-on energy (per pulse)*	E_{on}	Q_{rFWD} = 3,8 µC Q_{rFWD} = 7 µC				25 150		2,48 3,71		mWs
Turn-off energy (per pulse)*	E_{off}					25 150		1,84 2,91		

* L_S = 10 nH

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				35	25 125 150		1,76 1,73 1,70	2,05	V
Reverse leakage current	I_R			1200		25			7,7	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,19		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 1463 A/µs di/dt = 1493 A/µs	±15	600	35	25 150		30 34		A
Reverse recovery time	t_{rr}					25 150		298 493		ns
Recovered charge	Q_r					25 150		3,79 7,00		µC
Reverse recovered energy	E_{rec}					25 150		1,48 2,81		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 150		122 105		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,0012	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		35	25 150	1,58	1,87 2,30	2,07	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			5	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}	f= 1 Mhz	0	25		25		2000		pF
Reverse transfer capacitance	C_{res}							70		
Gate charge	Q_g		-15/15			25		270		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,82		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	35	25 125 150		167 165 165		ns
Rise time	t_r					25 125 150		52 54 54		
Turn-off delay time	$t_{d(off)}$					25 125 150		252 313 334		
Fall time	t_f					25 125 150		60 124 141		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 1,7 µC Q_{rFWD} = 3,1 µC Q_{rFWD} = 3,6 µC				25 125 150		3,06 3,73 3,86		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		2,10 3,37 3,74		

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Diode										
Static										
Forward voltage	V_F				10	25 150		1,77 1,68	2,05	V
Reverse leakage current	I_R			1200		25			2,7	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,91		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 656 A/µs di/dt = 564 A/µs di/dt = 533 A/µs	±15	600	35	25 125 150		10 12 13		A
Reverse recovery time	t_{rr}					25 125 150		394 574 653		ns
Recovered charge	Q_r					25 125 150		1,74 3,09 3,55		µC
Reverse recovered energy	E_{rec}					25 125 150		0,669 1,26 1,47		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		41 21 21		A/µs
Rectifier Diode										
Static										
Forward voltage	V_F				45	25 125		1,15 1,12		V
Reverse leakage current	I_R			1600		25			50	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,17		K/W

Characteristic Values

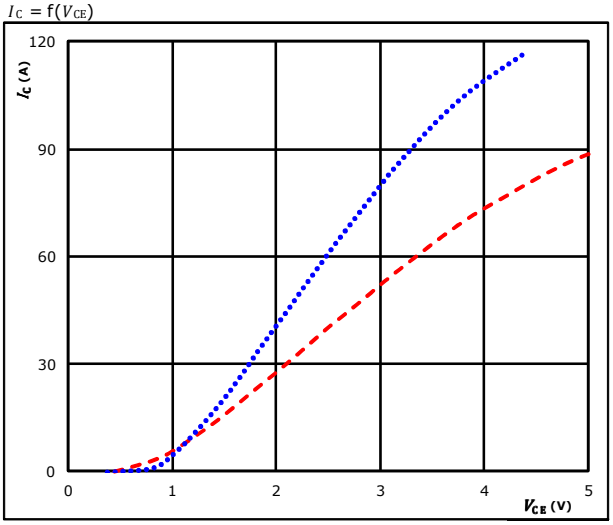
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Thermistor										
Rated resistance	R					25		5		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 493 Ω				100	-5		+5	%
Power dissipation	P					25		245		mW
Power dissipation constant						25		1,4		mW/K
B-value	$B_{(25/50)}$	Tol. ±2 %				25		3375		K
B-value	$B_{(25/100)}$	Tol. ±2 %				25		3437		K
Vincotech NTC Reference									K	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

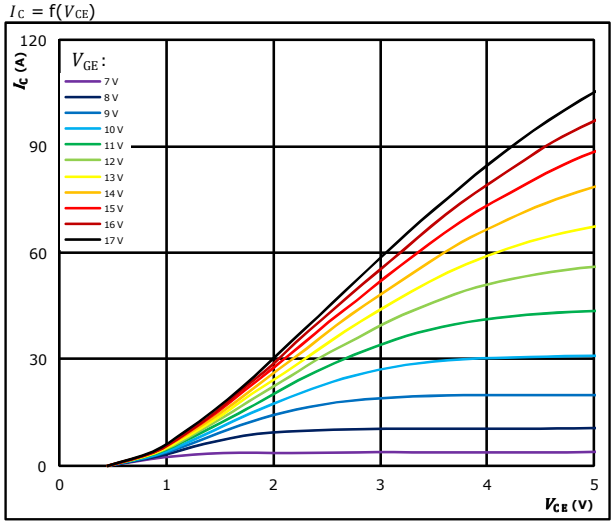


t_p =	250	µs	T_j:	25 °C	·····
V_{GE} =	15	V		150 °C	– – –

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

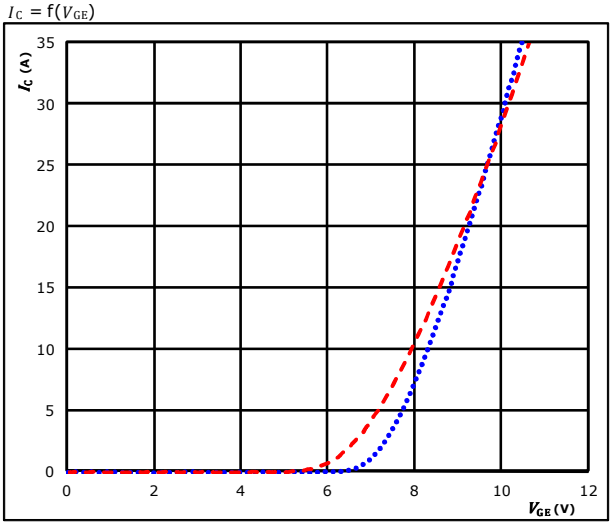


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

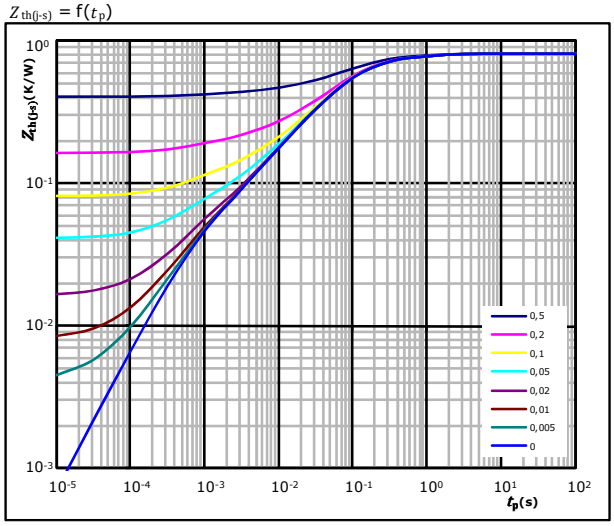


t_p =	100	µs	T_j:	25 °C	·····
V_{CE} =	10	V		150 °C	– – –

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,82	K/W

IGBT thermal model values

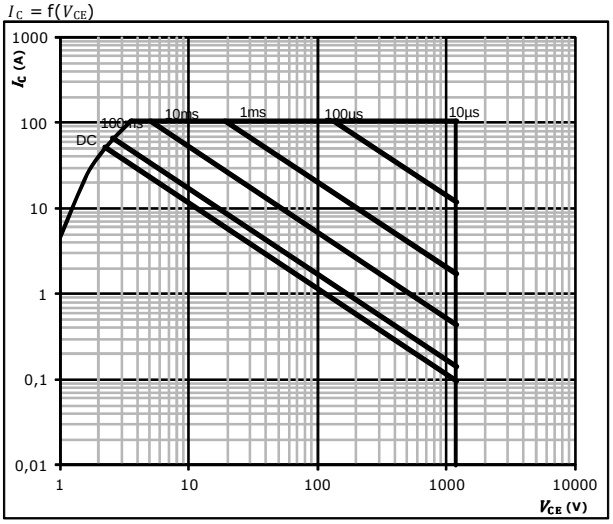
R (K/W)	τ (s)
1,04E-01	8,11E-01
3,36E-01	1,17E-01
2,58E-01	4,29E-02
8,09E-02	7,80E-03
3,79E-02	7,37E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



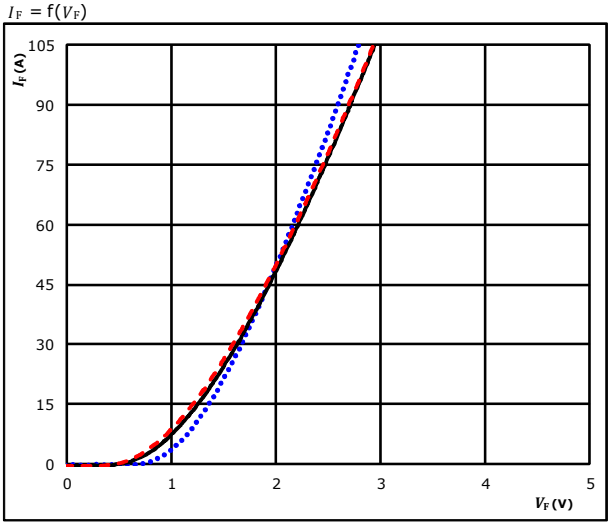
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



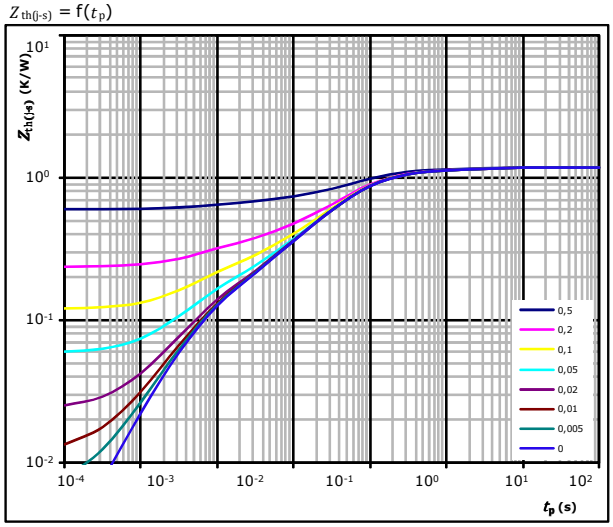
t_p = 250 µs

T_j: 25 °C
125 °C
150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,19 K/W

FWD thermal model values

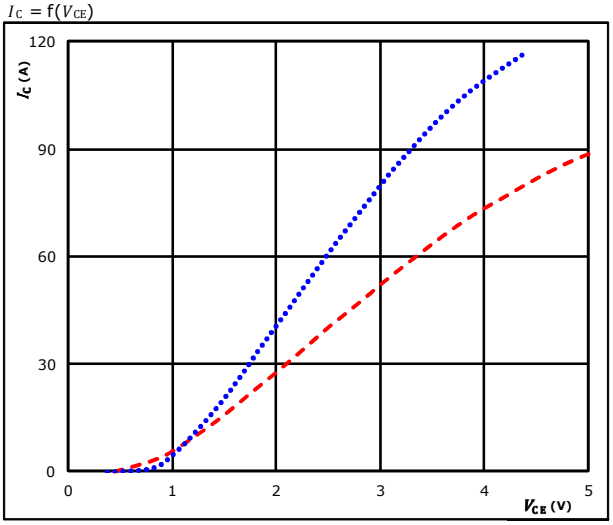
R (K/W)	τ (s)
6,30E-02	2,93E+00
1,30E-01	4,06E-01
5,50E-01	7,36E-02
2,26E-01	2,16E-02
1,15E-01	4,46E-03
9,49E-02	5,82E-04
8,50E-03	2,11E-04

Brake Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

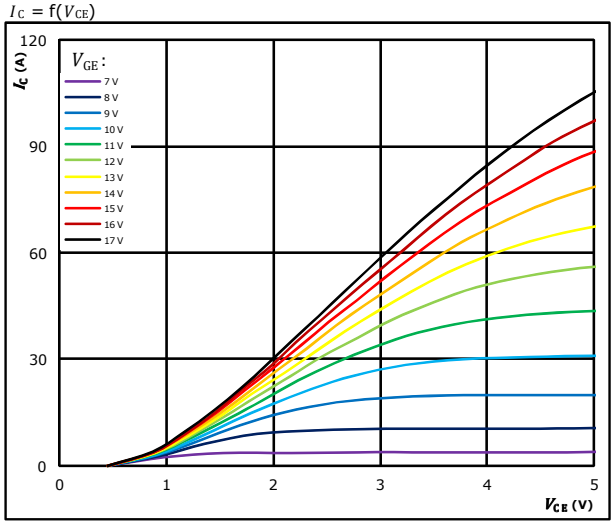


t_p =	250	µs	T_j:	25 °C	·····
V_{GE} =	15	V		150 °C	– – –

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

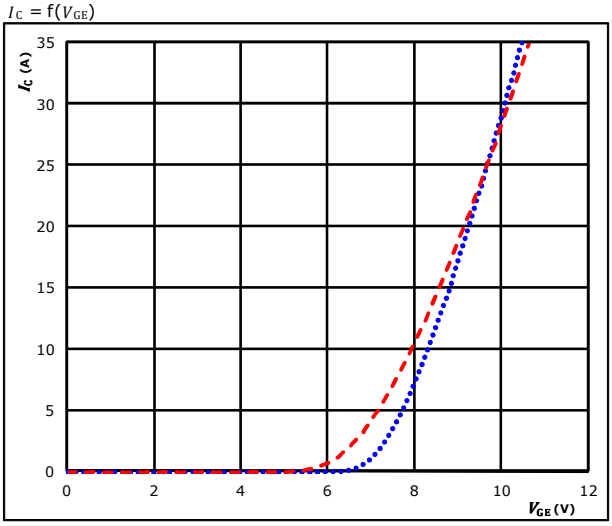


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

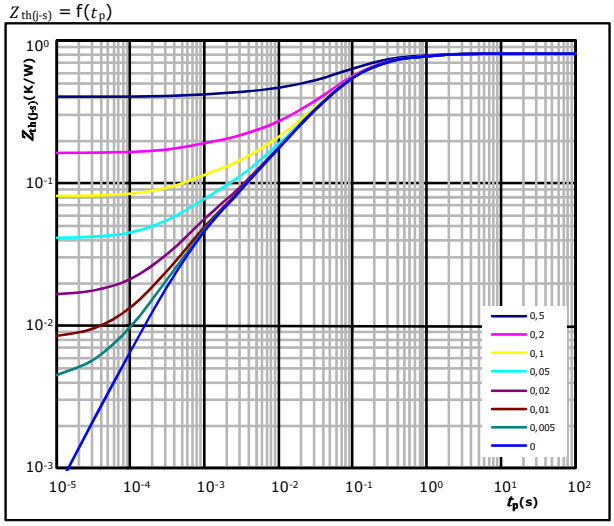


t_p =	100	µs	T_j:	25 °C	·····
V_{CE} =	10	V		150 °C	– – –

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,82	K/W

IGBT thermal model values

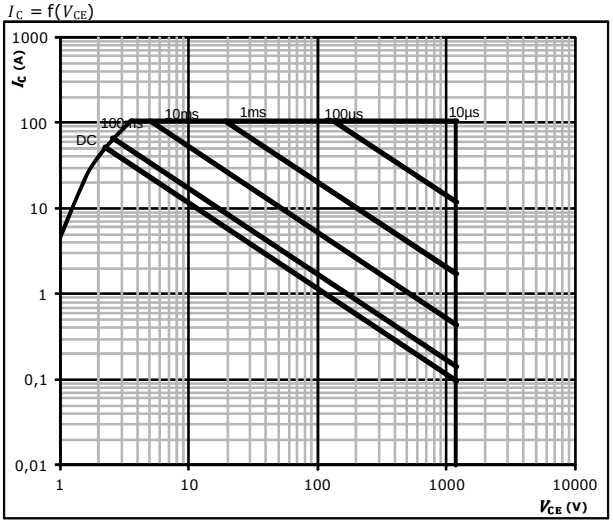
R (K/W)	τ (s)
1,04E-01	8,11E-01
3,36E-01	1,17E-01
2,58E-01	4,29E-02
8,09E-02	7,80E-03
3,79E-02	7,37E-04

Brake Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



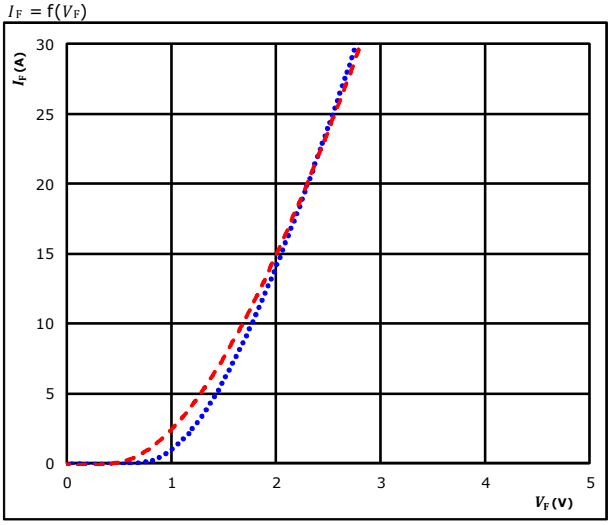
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Brake Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



t_p = 250 µs

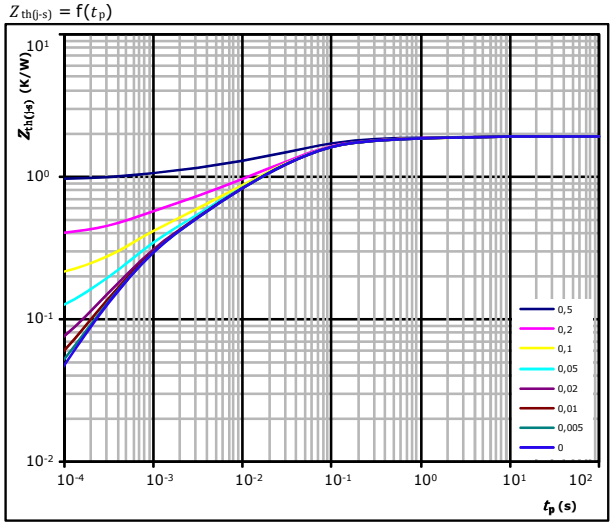
T_j: 25 °C

150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,91 K/W

FWD thermal model values

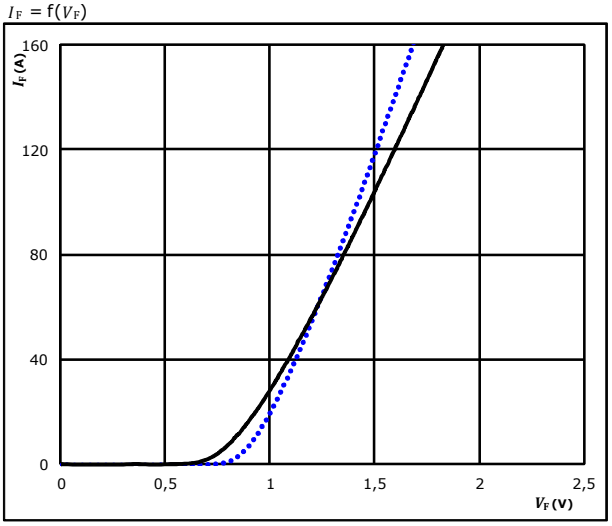
R (K/W)	τ (s)
6,90E-02	3,61E+00
1,74E-01	3,07E-01
8,07E-01	4,87E-02
3,70E-01	1,36E-02
2,79E-01	3,22E-03
2,10E-01	5,68E-04

Rectifier Diode Characteristics

figure 1. **Rectifier Diode**

Typical forward characteristics

$I_F = f(V_F)$



t_p = 250 µs

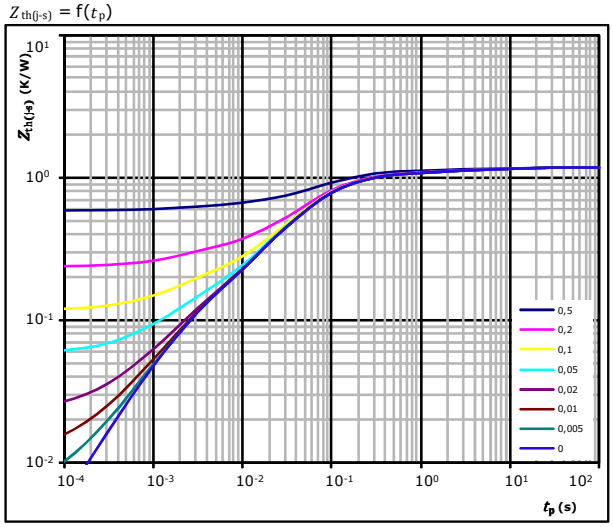
T_j: 25 °C

125 °C

figure 2. **Rectifier Diode**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,17 K/W

Diode thermal model values

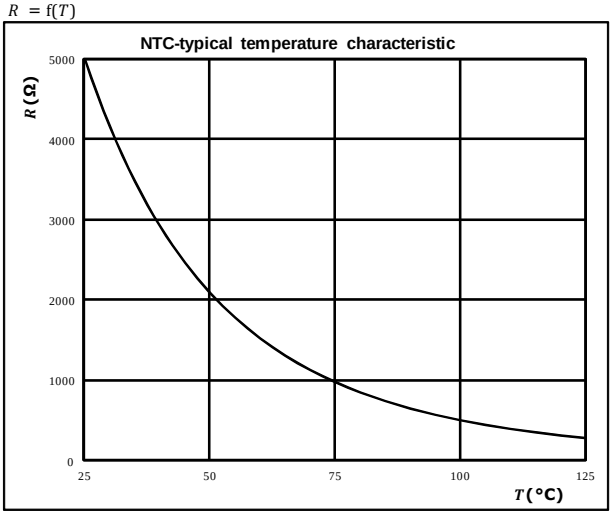
R (K/W)	τ (s)
7,71E-02	9,00E+00
1,19E-01	7,09E-01
4,99E-01	1,03E-01
3,97E-01	3,61E-02
8,19E-02	2,07E-03

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic
as a function of temperature

$R = f(T)$

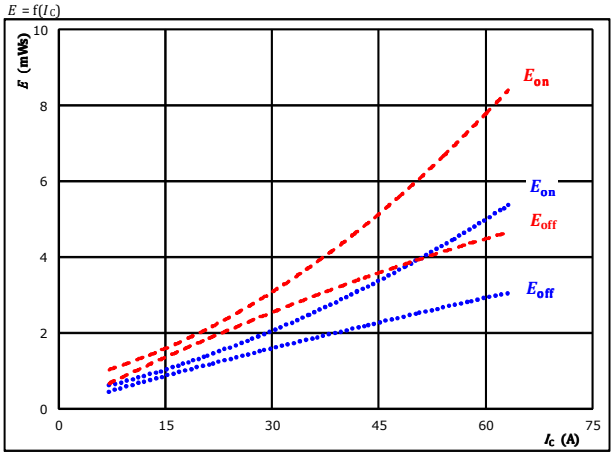


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



With an inductive load at

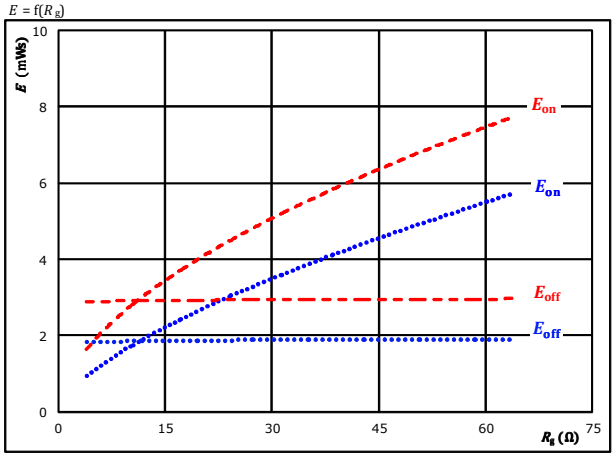
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω
R_{goff} =	16	Ω

T_j: 25 °C, 150 °C

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



With an inductive load at

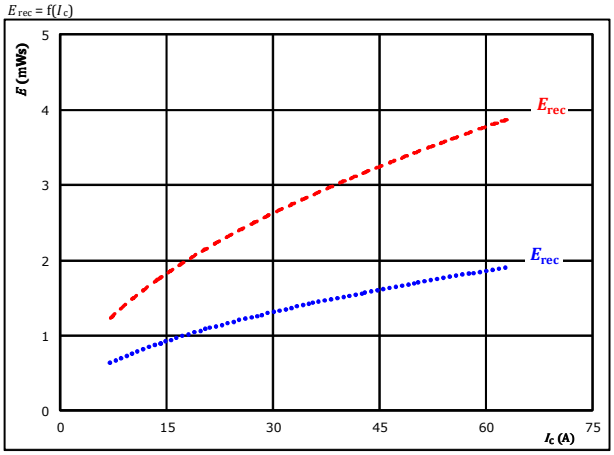
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

T_j: 25 °C, 150 °C

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



With an inductive load at

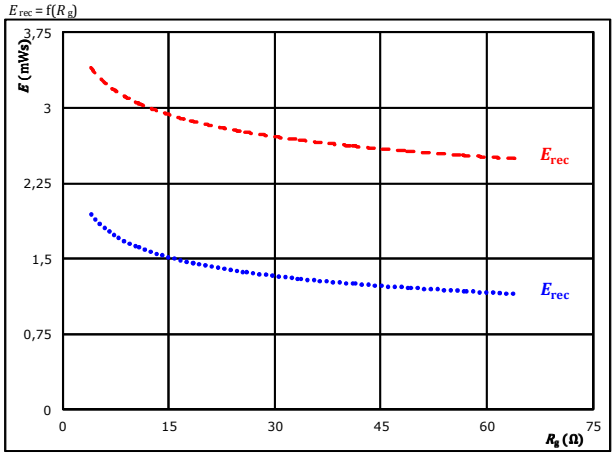
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω

T_j: 25 °C, 150 °C

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

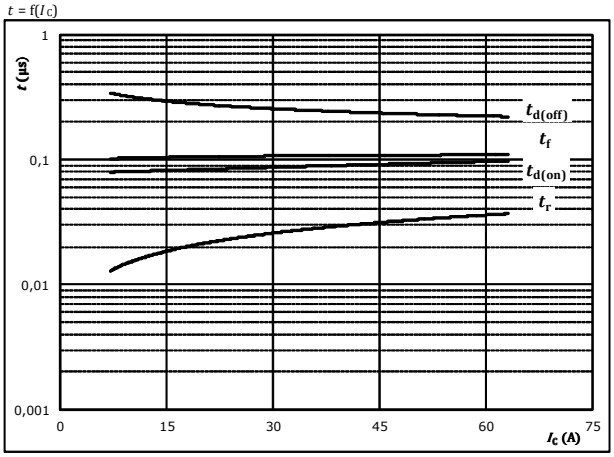
T_j: 25 °C, 150 °C

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



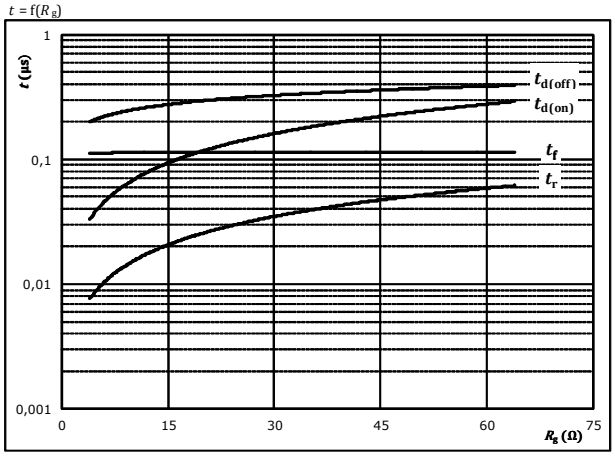
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω
R_{goff} =	16	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



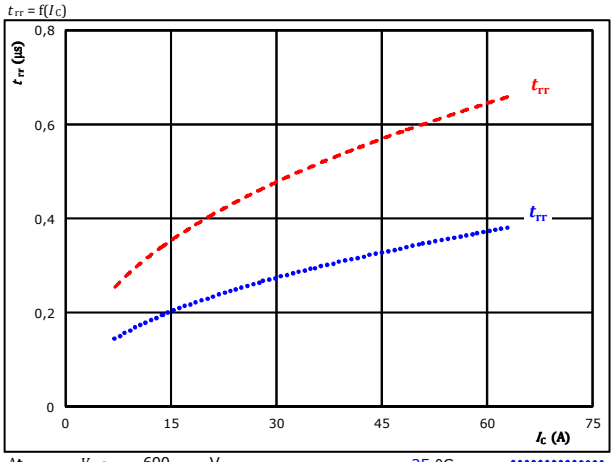
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



At

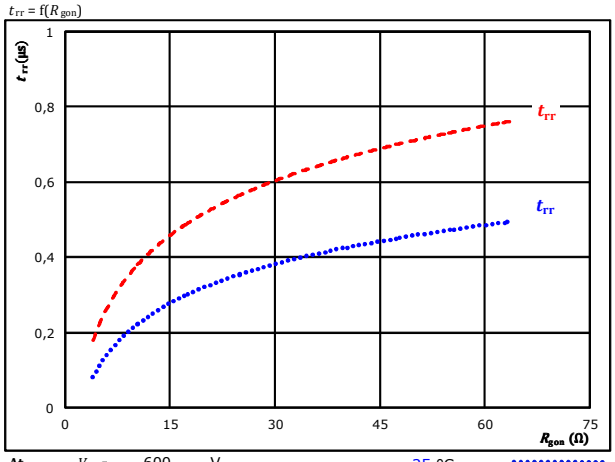
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω

T_j: 25 °C, 150 °C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



At

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

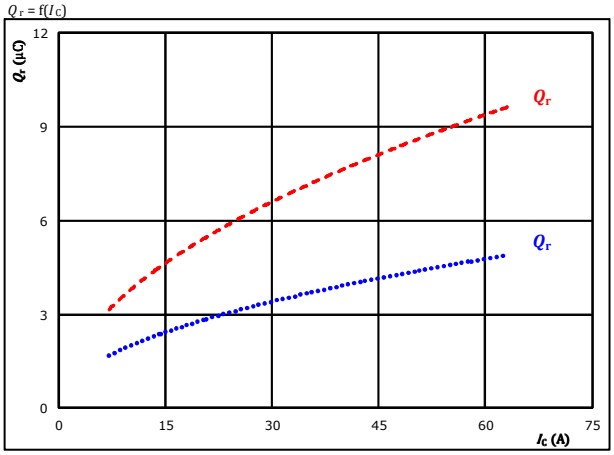
T_j: 25 °C, 150 °C

Inverter Switching Characteristics

figure 9. FWD

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

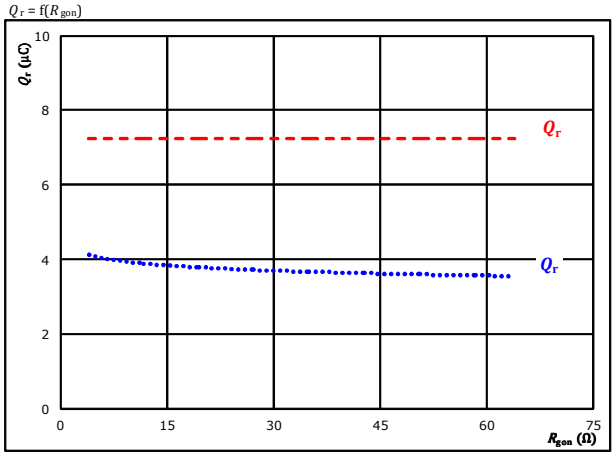


At						
	V_{CE} =	600	V	T_j:	25 °C	
	V_{GE} =	±15	V		150 °C	
	R_{gon} =	16	Ω			

figure 10. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

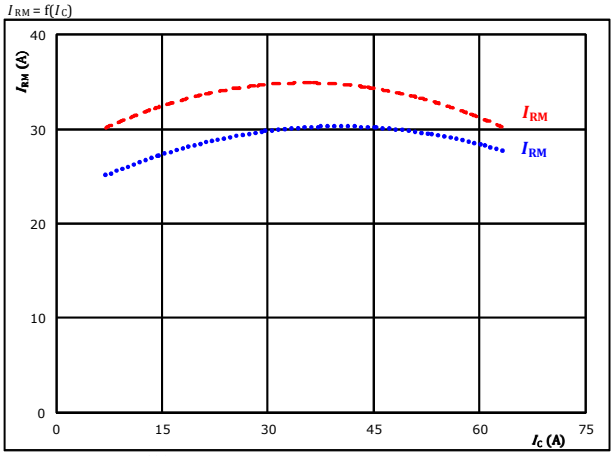


At						
	V_{CE}=	600	V	T_j:	25 °C	
	V_{GE} =	±15	V		150 °C	
	I_C=	35	A			

figure 11. FWD

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

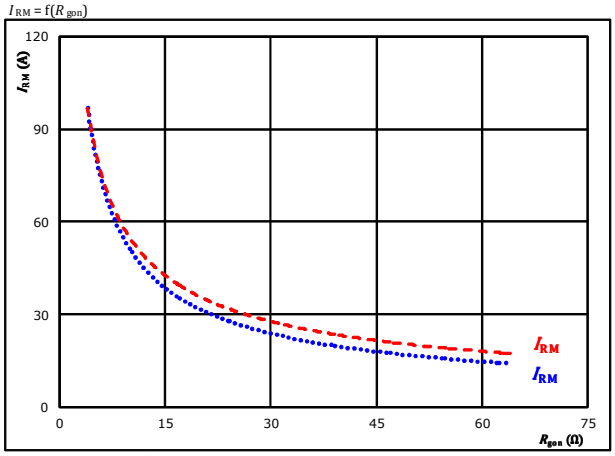


At						
	V_{CE}:	600	V	T_j:	25 °C	
	V_{GE} =	±15	V		150 °C	
	R_{gon} =	16	Ω			

figure 12. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



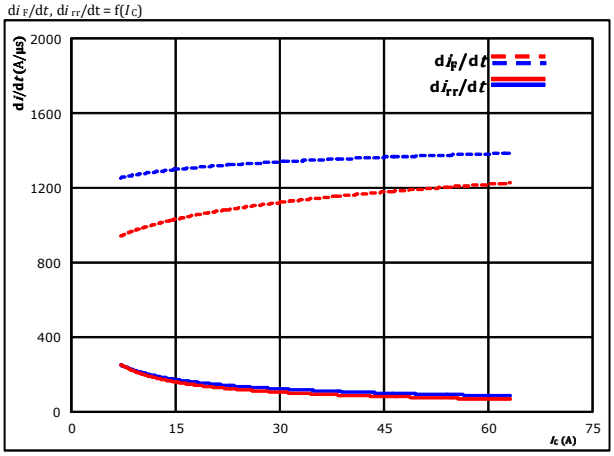
At						
	V_{CE} =	600	V	T_j:	25 °C	
	V_{GE} =	±15	V		150 °C	
	I_C =	35	A			

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$

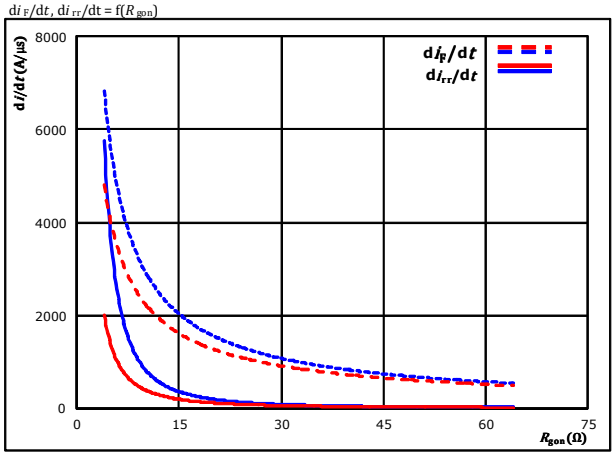


At					
V_{CE} =	600	V		25	°C
V_{GE} =	±15	V	T_j:	150	°C
R_{gon} =	16	Ω			

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$

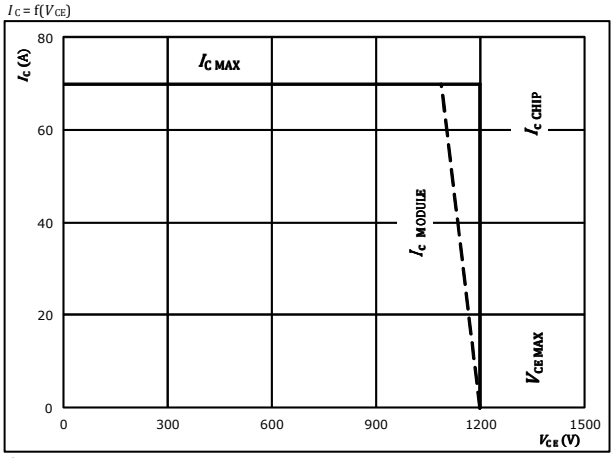


At					
V_{CE} =	600	V		25	°C
V_{GE} =	±15	V	T_j:	150	°C
I_C =	35	A			

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	175	°C
R_{gon} =	16	Ω
R_{goff} =	16	Ω

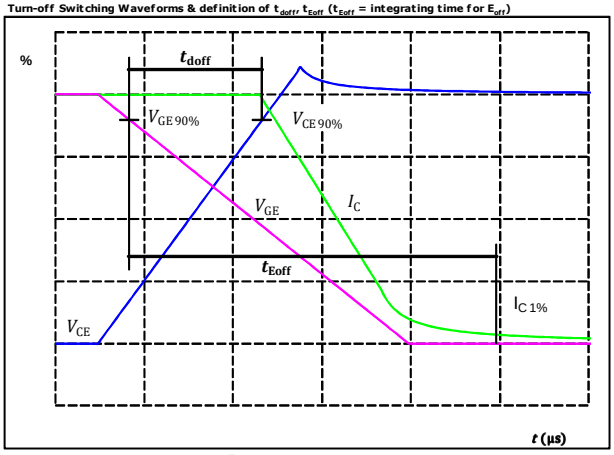
Inverter Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	16 Ω
R_{goff}	=	16 Ω

figure 1. IGBT

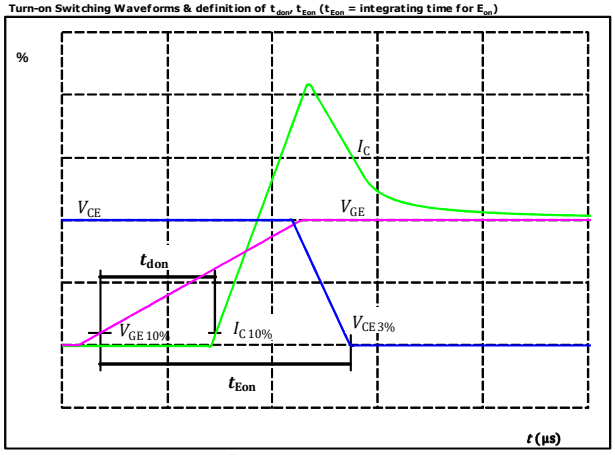
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	35	A
t_{doff} =	259	ns

figure 2. IGBT

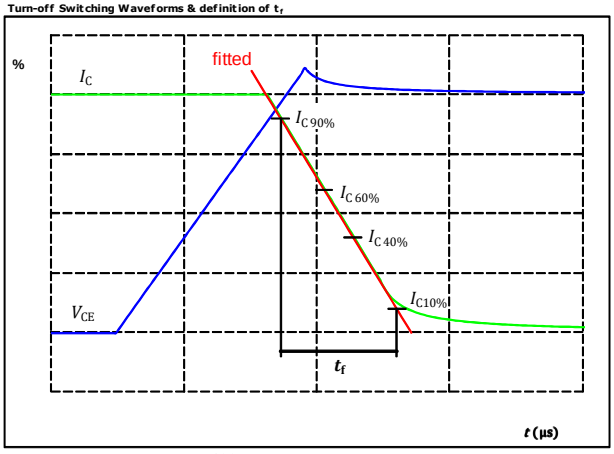
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	35	A
t_{don} =	89	ns

figure 3. IGBT

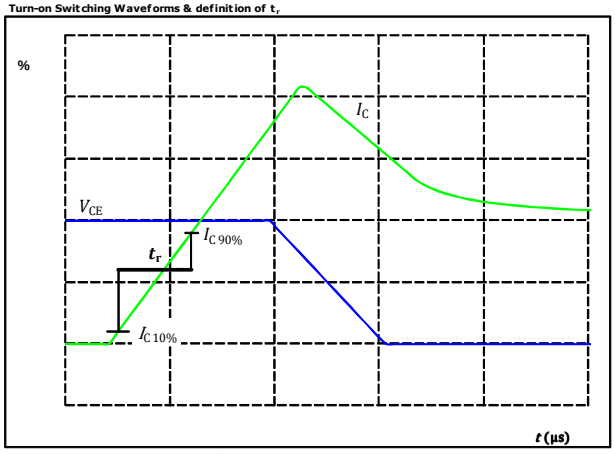
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	35	A
t_f =	115	ns

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

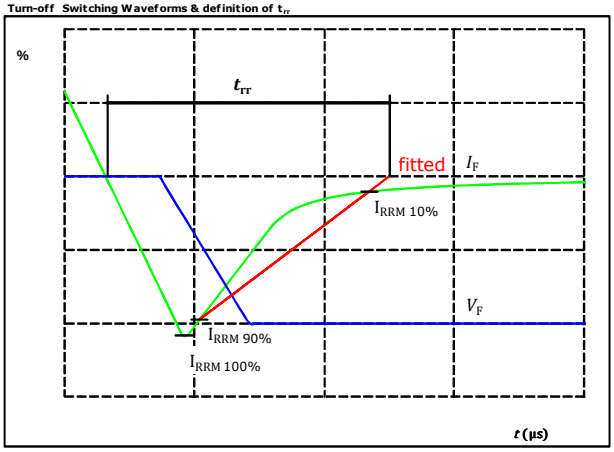


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	35	A
t_r =	26	ns

Inverter Switching Characteristics

figure 5. **FWD**

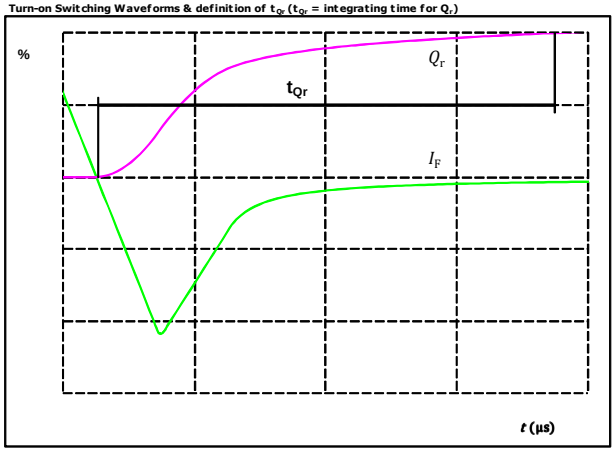
Turn-off Switching Waveforms & definition of t_{rr}



V_F (100%) =	600	V
I_F (100%) =	35	A
I_{RRM} (100%) =	34	A
t_{rr} =	493	ns

figure 6. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



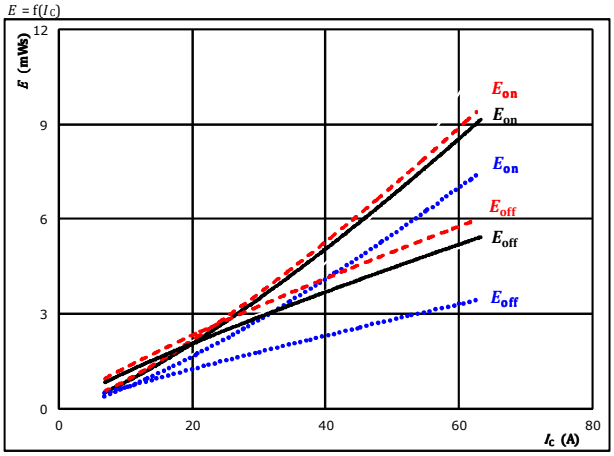
I_F (100%) =	35	A
Q_r (100%) =	7,00	µC

Brake Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



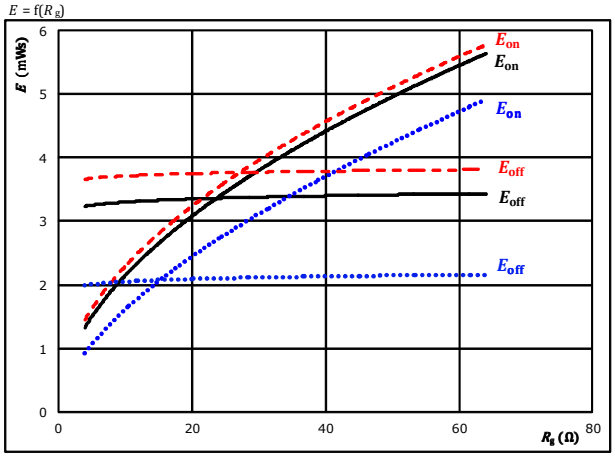
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C
R_{goff} =	32	Ω		

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



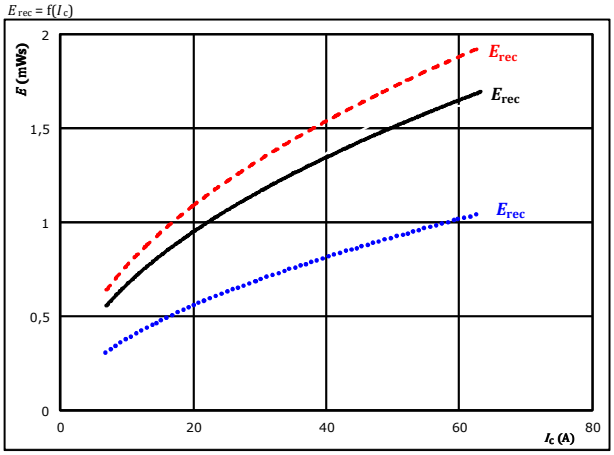
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	35	A		150 °C

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



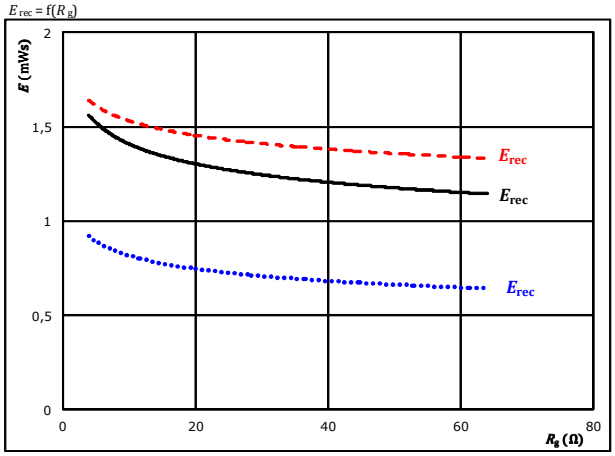
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

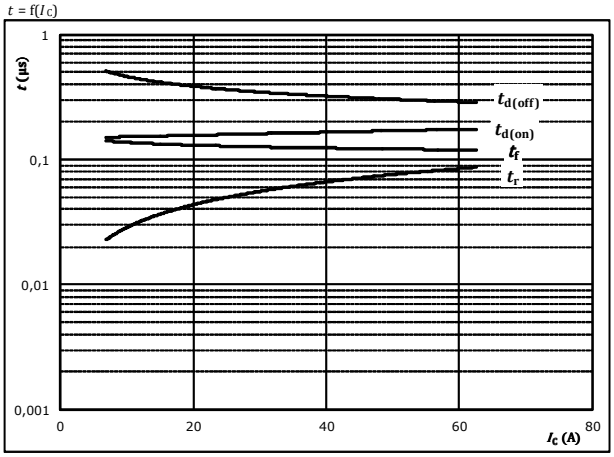
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	35	A		150 °C

Brake Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



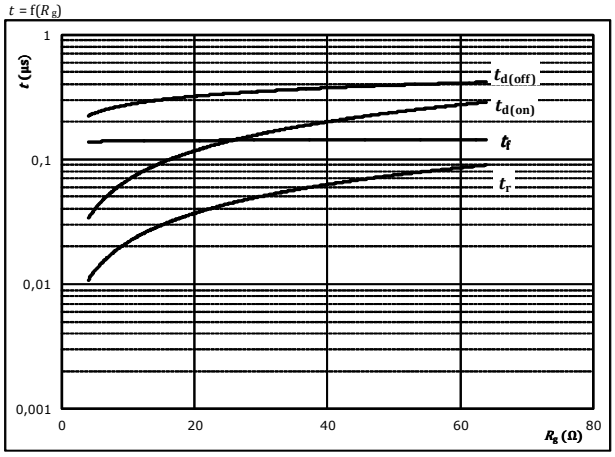
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



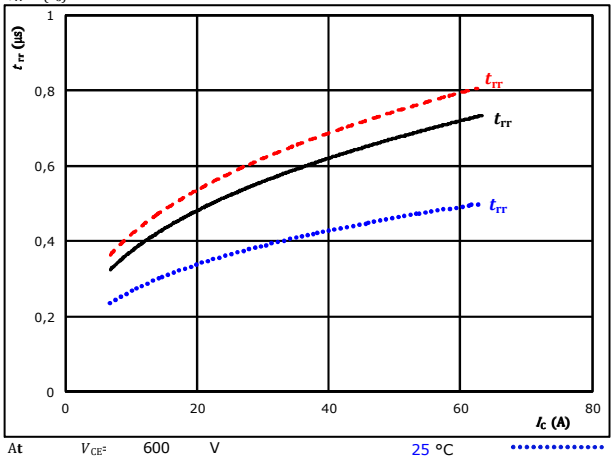
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	35	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

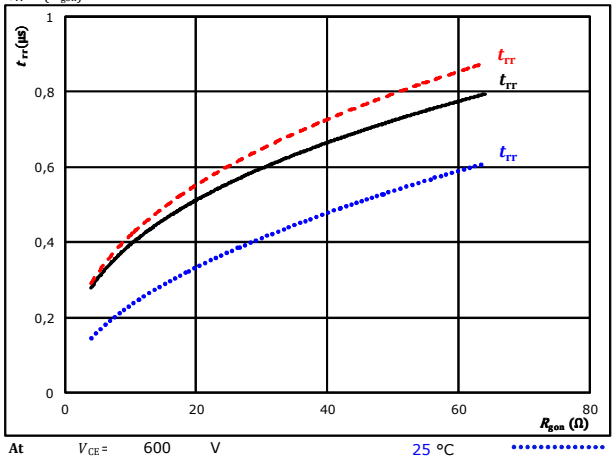


At	V_{CE} =	600	V		25 °C
	V_{GE} =	±15	V	T_j:	125 °C
	R_{gon} =	32	Ω		150 °C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



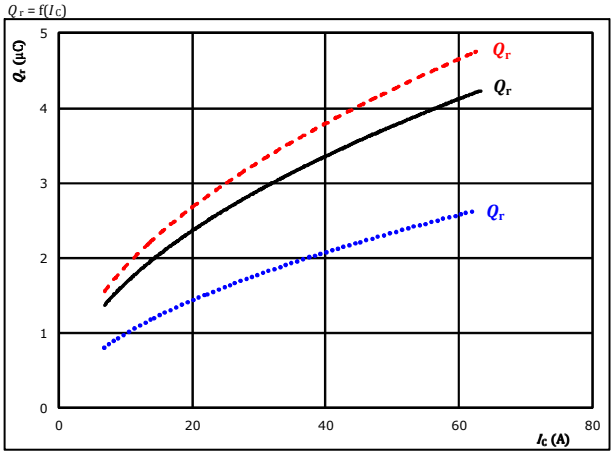
At	V_{CE} =	600	V		25 °C
	V_{GE} =	±15	V	T_j:	125 °C
	I_C =	35	A		150 °C

Brake Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

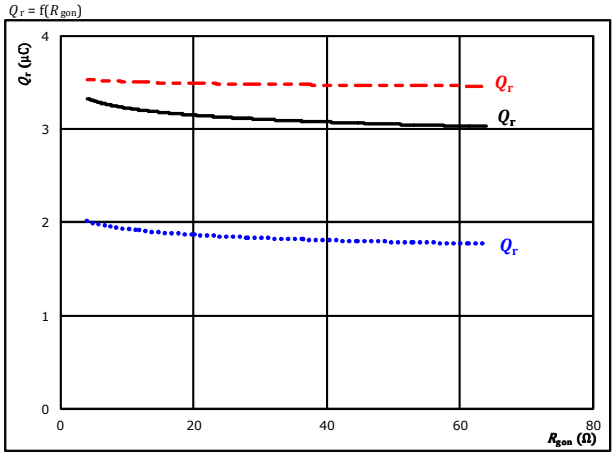


At					
V_{CE} =	600	V		25 °C	
V_{GE} =	±15	V	T_j:	125 °C	
R_{gon} =	32	Ω		150 °C	

figure 10. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

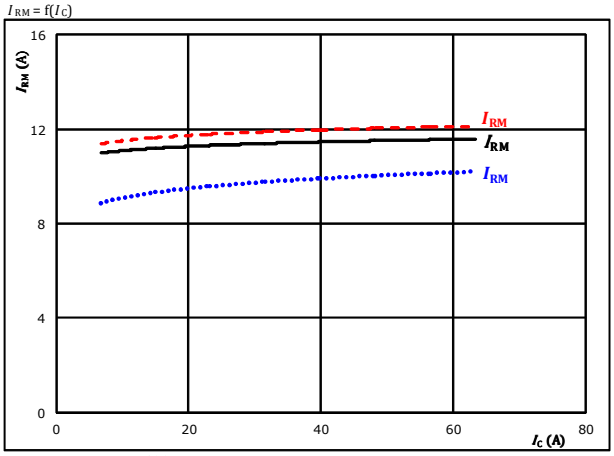


At					
V_{CE}=	600	V		25 °C	
V_{GE} =	±15	V	T_j:	125 °C	
I_C=	35	A		150 °C	

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

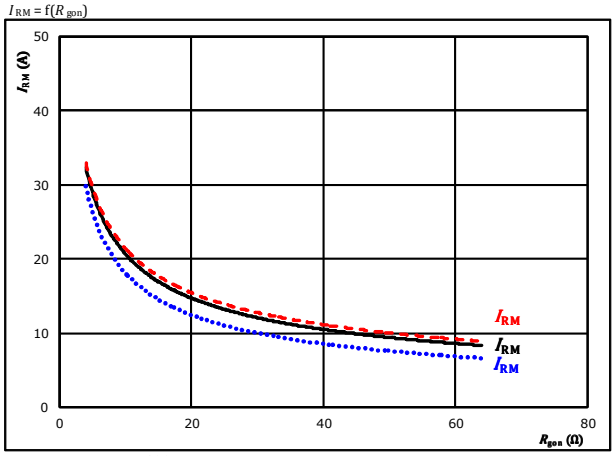


At					
V_{CE}:	600	V		25 °C	
V_{GE} =	±15	V	T_j:	125 °C	
R_{gon} =	32	Ω		150 °C	

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



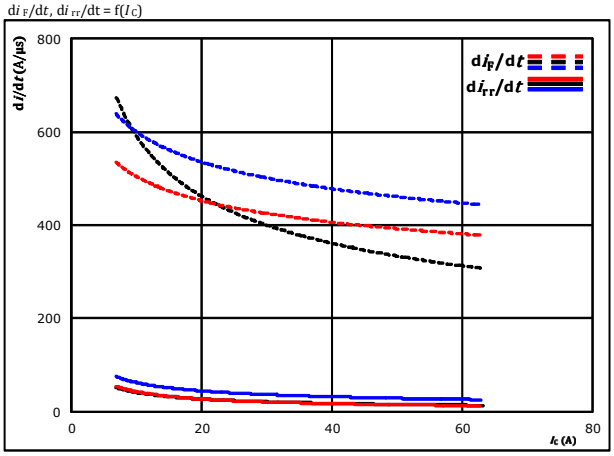
At					
V_{CE} =	600	V		25 °C	
V_{GE} =	±15	V	T_j:	125 °C	
I_C =	35	A		150 °C	

Brake Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_F/dt, di_{rr}/dt = f(I_C)$

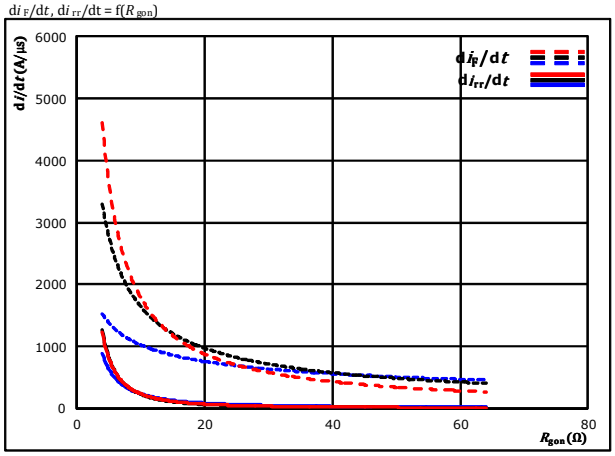


At	V_{CE} =	600	V	T_j:	25 °C	
	V_{GE} =	±15	V		125 °C	
	R_{gon} =	32	Ω		150 °C	

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$di_F/dt, di_{rr}/dt = f(R_{gon})$

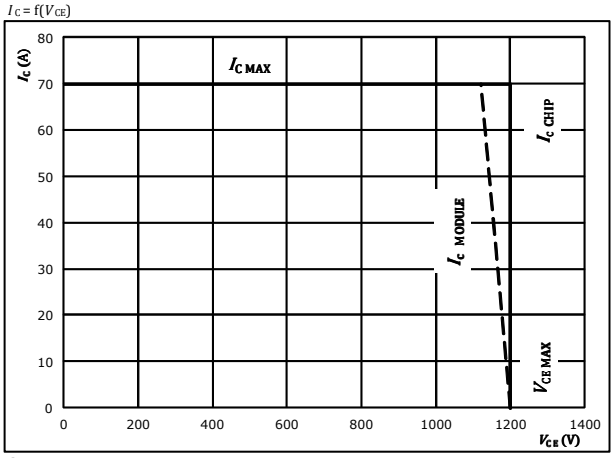


At	V_{CE} =	600	V	T_j:	25 °C	
	V_{GE} =	±15	V		125 °C	
	I_C =	35	A		150 °C	

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	125	°C	
R_{gon} =	32	Ω	
R_{goff} =	32	Ω	

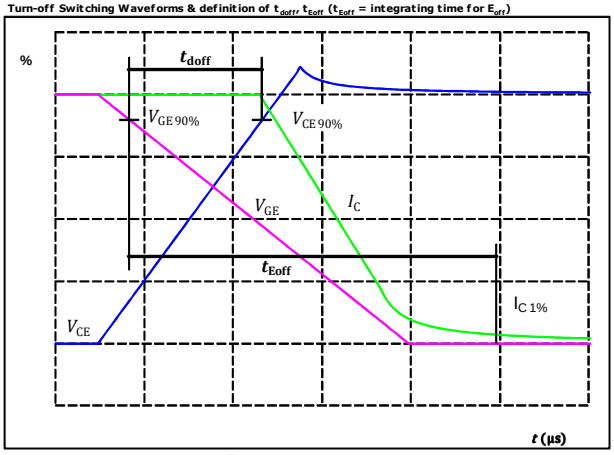
Brake Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

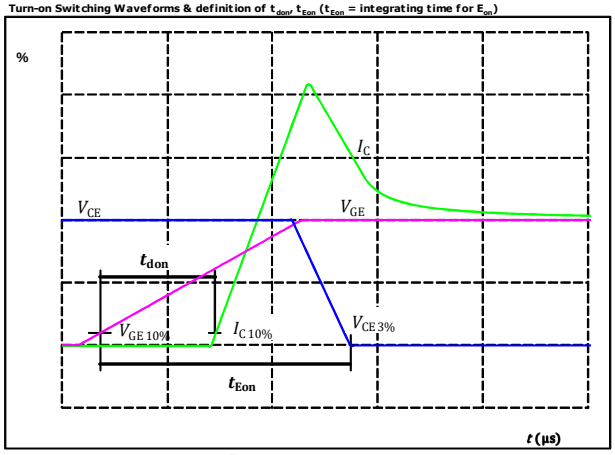
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	35	A
t_{doff} =	313	ns

figure 2. IGBT

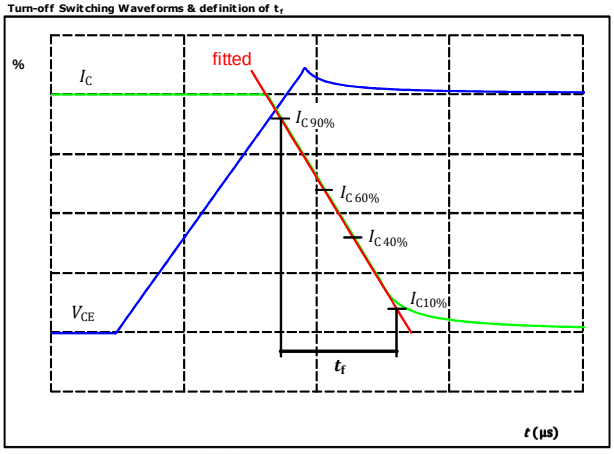
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	35	A
t_{don} =	165	ns

figure 3. IGBT

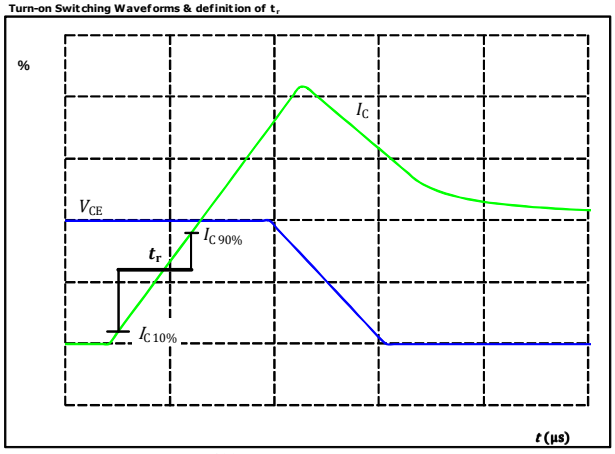
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	35	A
t_f =	124	ns

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

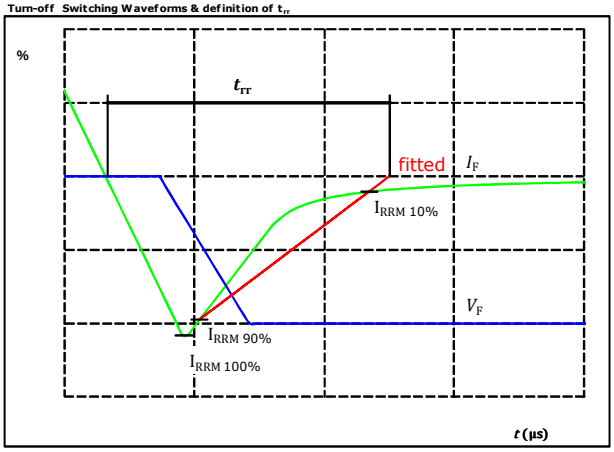


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	35	A
t_r =	54	ns

Brake Switching Characteristics

figure 5. **FWD**

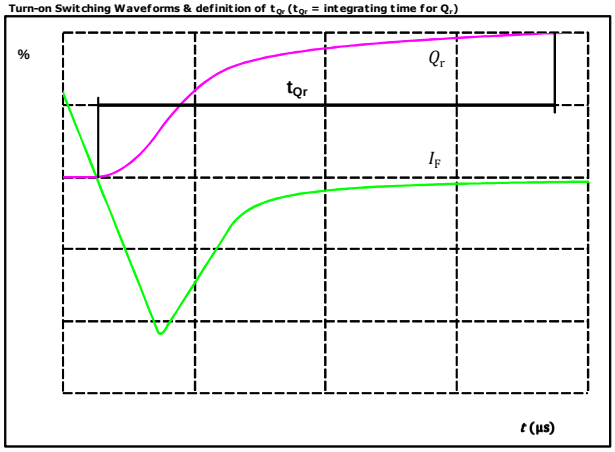
Turn-off Switching Waveforms & definition of t_{rr}



V_F (100%) =	600	V
I_F (100%) =	35	A
I_{RRM} (100%) =	12	A
t_{rr} =	574	ns

figure 6. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	35	A
Q_r (100%) =	3,09	µC

Vincotech

10-E212PMA035SC-L188A48Z
10-EY12PMA035SC-L188A48T
datasheet

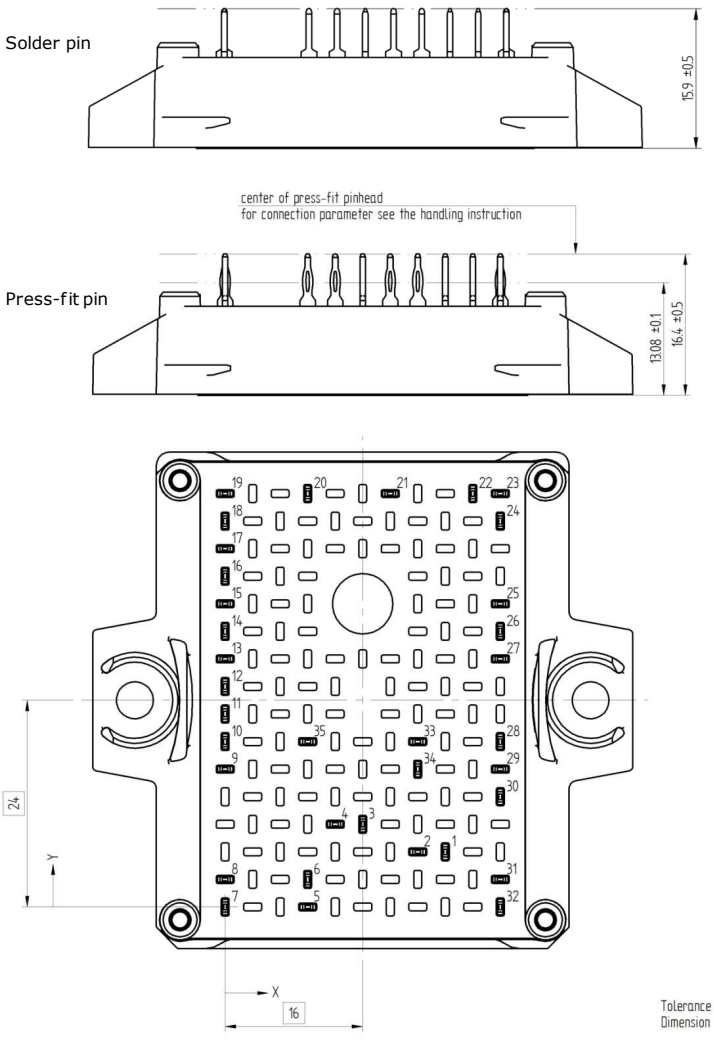
Ordering Code & Marking

Version	Ordering Code
without thermal paste 12 mm housing with solder pins	10-E212PMA035SC-L188A48Z
without thermal paste 12 mm housing with press-fit	10-EY12PMA035SC-L188A48T
with thermal paste 12 mm housing with solder pins	10-E212PMA035SC-L188A48Z-/3/
with thermal paste 12 mm housing with press-fit	10-EY12PMA035SC-L188A48T-/3/

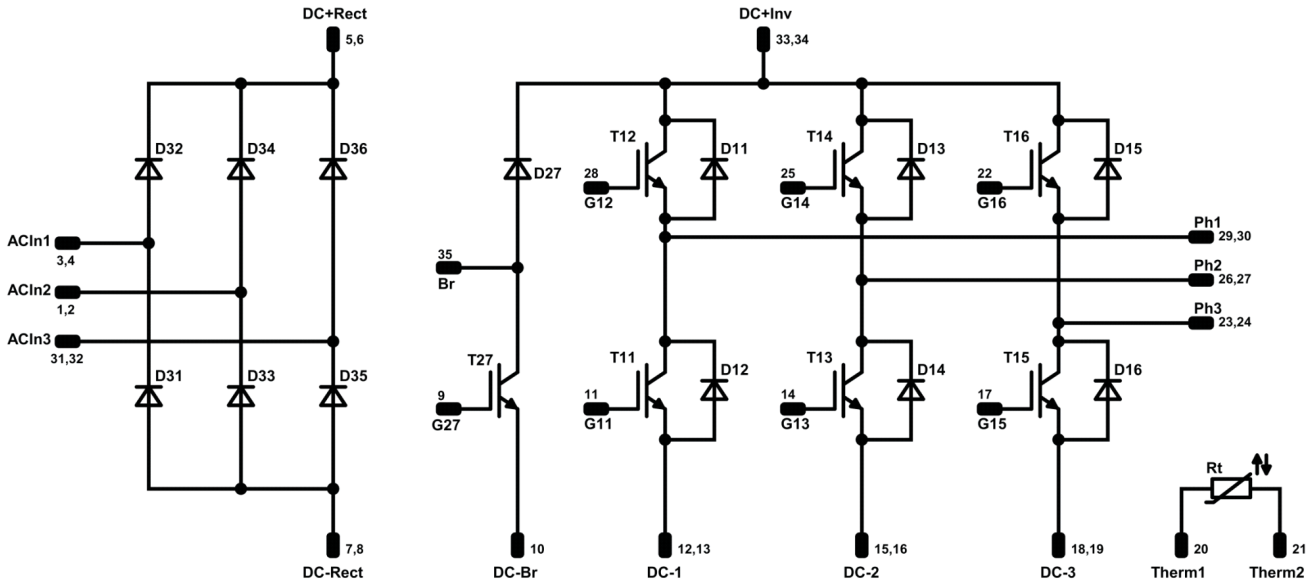
	Name		Date code	UL & VIN	Lot	Serial
Text	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
	Type&Ver	**Lot number**	**Serial**	**Date code**		
Datamatrix	TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

Pin table			
Pin	X	Y	Function
1	25,6	6,4	ACIn2
2	22,4	6,4	ACIn2
3	16	9,6	ACIn1
4	12,8	9,6	ACIn1
5	9,6	0	DC+Rect
6	9,6	3,2	DC+Rect
7	0	0	DC-Rect
8	0	3,2	DC-Rect
9	0	16	G27
10	0	19,2	DC-Br
11	0	22,4	G11
12	0	25,6	DC-1
13	0	28,8	DC-1
14	0	32	G13
15	0	35,2	DC-2
16	0	38,4	DC-2
17	0	41,6	G15
18	0	44,8	DC-3
19	0	48	DC-3
20	9,6	48	Therm1
21	19,2	48	Therm2
22	28,8	48	G16
23	32	48	Ph3
24	32	44,8	Ph3
25	32	35,2	G14
26	32	32	Ph2
27	32	28,8	Ph2
28	32	19,2	G12
29	32	16	Ph1
30	32	12,8	Ph1
31	32	3,2	ACIn3
32	32	0	ACIn3
33	22,4	19,2	DC+Inv
34	22,4	16	DC+Inv
35	9,6	19,2	Br



Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	35 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	35 A	Inverter Diode	
T27	IGBT	1200 V	35 A	Brake Switch	
D27	FWD	1200 V	10 A	Brake Diode	
D31, D32, D33, D34, D35, D36	Rectifier	1600 V	45 A	Rectifier Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* E2 packages see vincotech.com website.

Package data
Package data for *flow* E2 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-Ex12PMA035SC-L188A48x-D2-14	11 May. 2018	New housing,CTI,Cr&Cl	1,3,28